Correction to: Establishing a theoretical model for abrasive removal depth of silicon wafer chemical mechanical polishing by integrating a polishing times analytical model and specific down force energy theory

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The original version of this article unfortunately contained a mistake. The presentation of Fig. 8 was incorrect. The final version of this figure is provided here.

The online version of the original article can be found at <https://doi.org/10.1007/s00170-016-9345-2>.

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